Lattice Semiconductor Corporation - LFXP3C-4TN144I Datasheet

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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications,

Details	
Product Status	Obsolete
Number of LABs/CLBs	-
Number of Logic Elements/Cells	3000
Total RAM Bits	55296
Number of I/O	100
Number of Gates	-
Voltage - Supply	1.71V ~ 3.465V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	144-LQFP
Supplier Device Package	144-TQFP (20x20)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lfxp3c-4tn144i

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LatticeXP Family Data Sheet Introduction

July 2007 **Data Sheet DS1001**

Features

- **Non-volatile, Infinitely Reconfigurable**
  - Instant-on – powers up in microseconds
  - No external configuration memory
  - Excellent design security, no bit stream to intercept
  - Reconfigure SRAM based logic in milliseconds
  - SRAM and non-volatile memory programmable through system configuration and JTAG ports
- **Sleep Mode**
  - Allows up to 1000x static current reduction
- **TransFR™ Reconfiguration (TFR)**
  - In-field logic update while system operates
- **Extensive Density and Package Options**
  - 3.1K to 19.7K LUT4s
  - 62 to 340 I/Os
  - Density migration supported
- **Embedded and Distributed Memory**
  - 54 Kbits to 396 Kbits sysMEM™ Embedded Block RAM
  - Up to 79 Kbits distributed RAM
  - Flexible memory resources:
    - Distributed and block memory
- **Flexible I/O Buffer**
  - Programmable sysIO™ buffer supports wide range of interfaces:
    - LVCMOS 3.3/2.5/1.8/1.5/1.2
    - LVTTL
    - SSTL 18 Class I
    - SSTL 3/2 Class I, II
    - HSTL15 Class I, III
    - HSTL 18 Class I, II, III
    - PCI
    - LVDS, Bus-LVDS, LVPECL, RSDS
- **Dedicated DDR Memory Support**
  - Implements interface up to DDR333 (166MHz)
- **sysCLOCK™ PLLs**
  - Up to 4 analog PLLs per device
  - Clock multiply, divide and phase shifting
- **System Level Support**
  - IEEE Standard 1149.1 Boundary Scan, plus ispTRACY™ internal logic analyzer capability
  - Onboard oscillator for configuration
  - Devices operate with 3.3V, 2.5V, 1.8V or 1.2V power supply

Table 1-1. LatticeXP Family Selection Guide

Device	LFXP3	LFXP6	LFXP10	LFXP15	LFXP20
PFU/PFF Rows	16	24	32	40	44
PFU/PFF Columns	24	30	38	48	56
PFU/PFF (Total)	384	720	1216	1932	2464
LUTs (K)	3	6	10	15	20
Distributed RAM (KBits)	12	23	39	61	79
EBR SRAM (KBits)	54	72	216	324	396
EBR SRAM Blocks	6	8	24	36	44
V_{CC} Voltage	1.2/1.8/2.5/3.3V	1.2/1.8/2.5/3.3V	1.2/1.8/2.5/3.3V	1.2/1.8/2.5/3.3V	1.2/1.8/2.5/3.3V
PLLs	2	2	4	4	4
Max. I/O	136	188	244	300	340
Packages and I/O Combinations:					
100-pin TQFP (14 x 14 mm)	62				
144-pin TQFP (20 x 20 mm)	100	100			
208-pin PQFP (28 x 28 mm)	136	142			
256-ball fpBGA (17 x 17 mm)		188	188	188	188
388-ball fpBGA (23 x 23 mm)			244	268	268
484-ball fpBGA (23 x 23 mm)				300	340

Introduction

The LatticeXP family of FPGA devices combine logic gates, embedded memory and high performance I/Os in a single architecture that is both non-volatile and infinitely reconfigurable to support cost-effective system designs.

The re-programmable non-volatile technology used in the LatticeXP family is the next generation ispXP™ technology. With this technology, expensive external configuration memories are not required and designs are secured from unauthorized read-back. In addition, instant-on capability allows for easy interfacing in many applications.

The ispLEVER® design tool from Lattice allows large complex designs to be efficiently implemented using the LatticeXP family of FPGA devices. Synthesis library support for LatticeXP is available for popular logic synthesis tools. The ispLEVER tool uses the synthesis tool output along with the constraints from its floor planning tools to place and route the design in the LatticeXP device. The ispLEVER tool extracts the timing from the routing and back-annotates it into the design for timing verification.

Lattice provides many pre-designed IP (Intellectual Property) ispLeverCORE™ modules for the LatticeXP family. By using these IPs as standardized blocks, designers are free to concentrate on the unique aspects of their design, increasing their productivity.

Figure 2-8. Per Quadrant Secondary Clock Selection

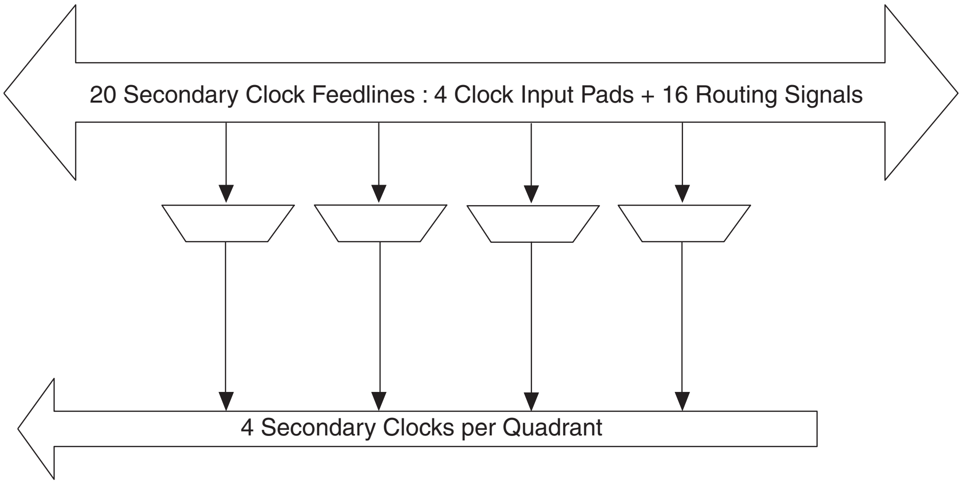
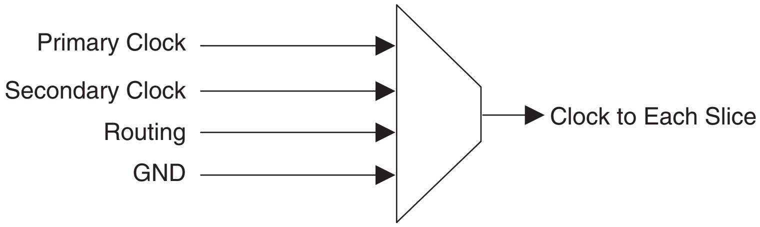


Figure 2-9. Slice Clock Selection



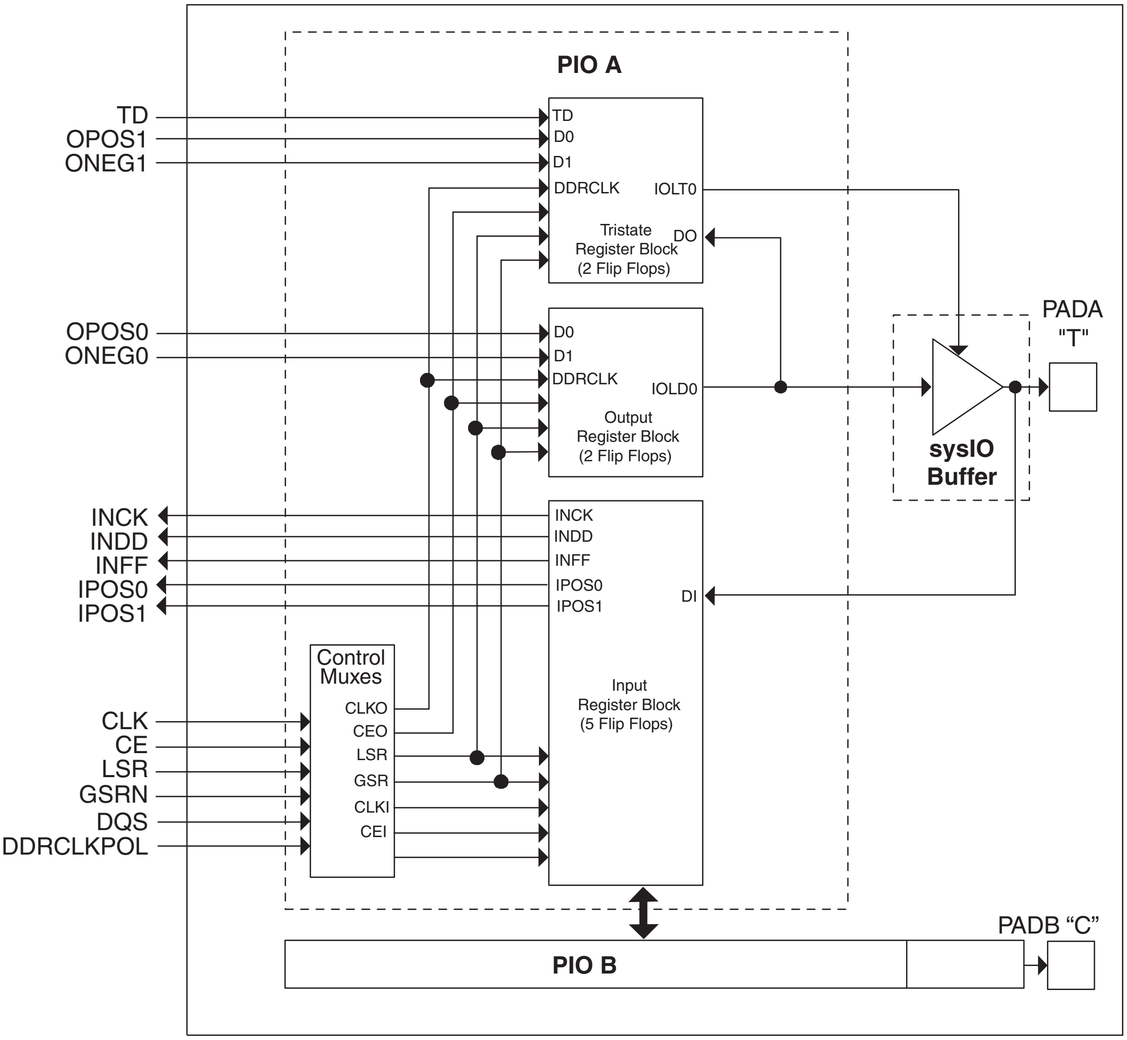
sysCLOCK Phase Locked Loops (PLLs)

The PLL clock input, from pin or routing, feeds into an input clock divider. There are three sources of feedback signals to the feedback divider: from CLKOP (PLL internal), from clock net (CLKOP or CLKOS) or from a user clock (PIN or logic). There is a PLL_LOCK signal to indicate that VCO has locked on to the input clock signal. Figure 2-10 shows the sysCLOCK PLL diagram.

The setup and hold times of the device can be improved by programming a delay in the feedback or input path of the PLL which will advance or delay the output clock with reference to the input clock. This delay can be either programmed during configuration or can be adjusted dynamically. In dynamic mode, the PLL may lose lock after adjustment and not relock until the t_{LOCK} parameter has been satisfied. Additionally, the phase and duty cycle block allows the user to adjust the phase and duty cycle of the CLKOS output.

The sysCLOCK PLLs provide the ability to synthesize clock frequencies. Each PLL has four dividers associated with it: input clock divider, feedback divider, post scalar divider and secondary clock divider. The input clock divider is used to divide the input clock signal, while the feedback divider is used to multiply the input clock signal. The post scalar divider allows the VCO to operate at higher frequencies than the clock output, thereby increasing the frequency range. The secondary divider is used to derive lower frequency outputs.

Figure 2-17. PIC Diagram



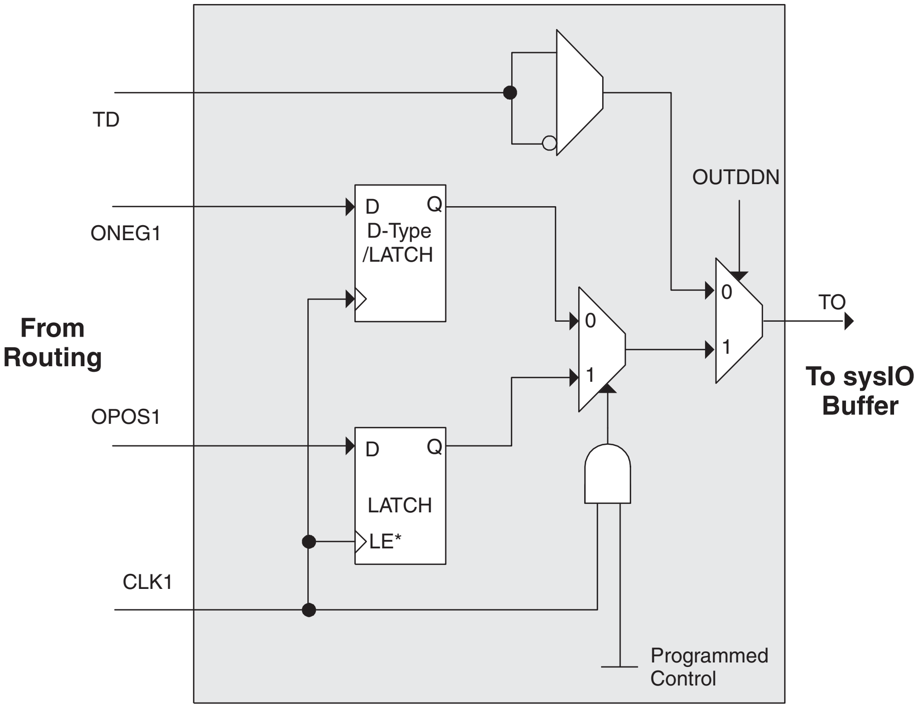
In the LatticeXP family, seven PIOs or four (3.5) PICs are grouped together to provide two LVDS differential pairs, one PIC pair and one single I/O, as shown in Figure 2-18.

Two adjacent PIOs can be joined to provide a differential I/O pair (labeled as “T” and “C”). The PAD Labels “T” and “C” distinguish the two PIOs. Only the PIO pairs on the left and right edges of the device can be configured as LVDS transmit/receive pairs.

One of every 14 PIOs (a group of 8 PICs) contains a delay element to facilitate the generation of DQS signals as shown in Figure 2-19. The DQS signal feeds the DQS bus which spans the set of 13 PIOs (8 PICs). The DQS signal from the bus is used to strobe the DDR data from the memory into input register blocks. This interface is designed for memories that support one DQS strobe per eight bits of data.

The exact DQS pins are shown in a dual function in the Logic Signal Connections table in this data sheet. Additional detail is provided in the Signal Descriptions table in this data sheet.

Figure 2-25. Tristate Register Block



*Latch is transparent when input is low.

Control Logic Block

The control logic block allows the selection and modification of control signals for use in the PIO block. A clock is selected from one of the clock signals provided from the general purpose routing and a DQS signal provided from the programmable DQS pin. The clock can optionally be inverted.

The clock enable and local reset signals are selected from the routing and optionally inverted. The global tristate signal is passed through this block.

DDR Memory Support

Implementing high performance DDR memory interfaces requires dedicated DDR register structures in the input (for read operations) and in the output (for write operations). As indicated in the PIO Logic section, the LatticeXP devices provide this capability. In addition to these registers, the LatticeXP devices contain two elements to simplify the design of input structures for read operations: the DQS delay block and polarity control logic.

DLL Calibrated DQS Delay Block

Source Synchronous interfaces generally require the input clock to be adjusted in order to correctly capture data at the input register. For most interfaces a PLL is used for this adjustment, however in DDR memories the clock (referred to as DQS) is not free running so this approach cannot be used. The DQS Delay block provides the required clock alignment for DDR memory interfaces.

The DQS signal (selected PIOs only) feeds from the PAD through a DQS delay element to a dedicated DQS routing resource. The DQS signal also feeds the polarity control logic which controls the polarity of the clock to the sync registers in the input register blocks. Figures 2-26 and 2-27 show how the polarity control logic are routed to the PIOs.

The temperature, voltage and process variations of the DQS delay block are compensated by a set of calibration (6-bit bus) signals from two DLLs on opposite sides of the device. Each DLL compensates DQS Delays in its half of the device as shown in Figure 2-27. The DLL loop is compensated for temperature, voltage and process variations by the system clock and feedback loop.

Hot Socketing Specifications[1, 2, 3, 4, 5, 6]

Symbol	Parameter	Condition	Min.	Typ.	Max.	Units
I_{DK}	Input or I/O Leakage Current	$0 \le V_{IN} \le V_{IH}$ (MAX.)	—	—	+/-1000	µA

1. Insensitive to sequence of V_{CC}, V_{CCAUX} and V_{CCIO}. However, assumes monotonic rise/fall rates for V_{CC}, V_{CCAUX} and V_{CCIO}.
2. $0 \le V_{CC} \le V_{CC}$ (MAX) or $0 \le V_{CCAUX} \le V_{CCAUX}$ (MAX).
3. $0 \le V_{CCIO} \le V_{CCIO}$ (MAX) for top and bottom I/O banks.
4. $0.2 \le V_{CCIO} \le V_{CCIO}$ (MAX) for left and right I/O banks.
5. I_{DK} is additive to I_{PU}, I_{PW} or I_{BH}.
6. LVCMOS and LVTTL only.

sysIO Differential Electrical Characteristics

LVDS

Over Recommended Operating Conditions

Parameter Symbol	Parameter Description	Test Conditions	Min.	Typ.	Max.	Units
V_{INP}, V_{INM}	Input Voltage		0	—	2.4	V
V_{THD}	Differential Input Threshold		+/-100	—	—	mV
V_{CM}	Input Common Mode Voltage	$100mV \leq V_{THD}$	$V_{THD}/2$	1.2	1.8	V
		$200mV \leq V_{THD}$	$V_{THD}/2$	1.2	1.9	V
		$350mV \leq V_{THD}$	$V_{THD}/2$	1.2	2.0	V
I_{IN}	Input current	Power on or power off	—	—	+/-10	µA
V_{OH}	Output high voltage for V_{OP} or V_{OM}	R_T = 100 ohms	—	1.38	1.60	V
V_{OL}	Output low voltage for V_{OP} or V_{OM}	R_T = 100 ohms	0.9V	1.03	—	V
V_{OD}	Output voltage differential	$(V_{OP} - V_{OM})$, R_T = 100 ohms	250	350	450	mV
ΔV_{OD}	Change in V_{OD} between high and low		—	—	50	mV
V_{OS}	Output voltage offset	$(V_{OP} - V_{OM})/2$, R_T = 100 ohms	1.125	1.25	1.375	V
ΔV_{OS}	Change in V_{OS} between H and L		—	—	50	mV
I_{OSD}	Output short circuit current	V_{OD} = 0V Driver outputs shorted	—	—	6	mA

Figure 3-4. RSDS (Reduced Swing Differential Standard)

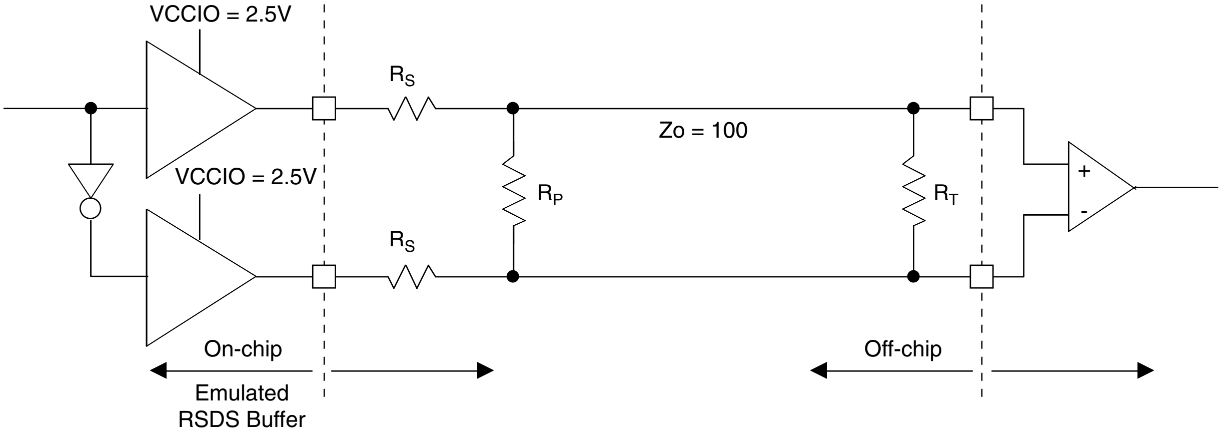


Table 3-4. RSDS DC Conditions

Parameter	Description	Typical	Units
Z_{OUT}	Output impedance	20	ohms
R_S	Driver series resistor	300	ohms
R_P	Driver parallel resistor	121	ohms
R_T	Receiver termination	100	ohms
V_{OH}	Output high voltage	1.35	V
V_{OL}	Output low voltage	1.15	V
V_{OD}	Output differential voltage	0.20	V
V_{CM}	Output common mode voltage	1.25	V
Z_{BACK}	Back impedance	101.5	ohms
I_{DC}	DC output current	3.66	mA

Switching Test Conditions

Figure 3-13 shows the output test load that is used for AC testing. The specific values for resistance, capacitance, voltage, and other test conditions are shown in Figure 3-5.

Figure 3-13. Output Test Load, LVTTL and LVCMOS Standards

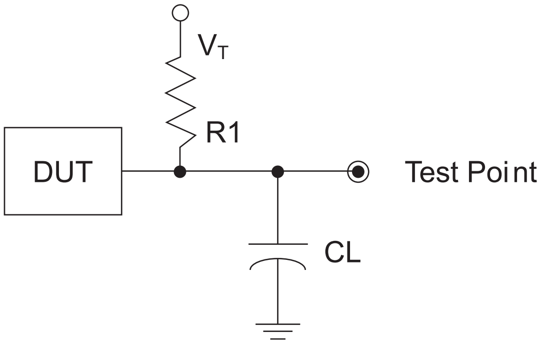


Table 3-5. Test Fixture Required Components, Non-Terminated Interfaces

Test Condition	R_1	C_L	Timing Ref.	V_T
LVTTL and other LVCMOS settings (L -> H, H -> L)	∞	0pF	LVCMOS 3.3 = 1.5V	—
			LVCMOS 2.5 = $V_{CCIO}/2$	—
			LVCMOS 1.8 = $V_{CCIO}/2$	—
			LVCMOS 1.5 = $V_{CCIO}/2$	—
			LVCMOS 1.2 = $V_{CCIO}/2$	—
LVCMOS 2.5 I/O (Z -> H)	188	0pF	$V_{CCIO}/2$	V_{OL}
LVCMOS 2.5 I/O (Z -> L)			$V_{CCIO}/2$	V_{OH}
LVCMOS 2.5 I/O (H -> Z)			V_{OH} - 0.15	V_{OL}
LVCMOS 2.5 I/O (L -> Z)			V_{OL} + 0.15	V_{OH}

Note: Output test conditions for all other interfaces are determined by the respective standards.

Signal Descriptions (Cont.)

Signal Name	I/O	Descriptions
Test and Programming (Dedicated pins. Pull-up is enabled on input pins during configuration.)		
TMS	I	Test Mode Select input, used to control the 1149.1 state machine.
TCK	I	Test Clock input pin, used to clock the 1149.1 state machine.
TDI	I	Test Data in pin, used to load data into device using 1149.1 state machine. After power-up, this TAP port can be activated for configuration by sending appropriate command. (Note: once a configuration port is selected it is locked. Another configuration port cannot be selected until the power-up sequence).
TDO	O	Output pin -Test Data out pin used to shift data out of device using 1149.1.
V_{CCJ}	—	V_{CCJ} - The power supply pin for JTAG Test Access Port.
Configuration Pads (used during sysCONFIG)		
CFG[1:0]	I	Mode pins used to specify configuration modes values latched on rising edge of INITN. During configuration, a pull-up is enabled.
INITN	I/O	Open Drain pin - Indicates the FPGA is ready to be configured. During configuration, a pull-up is enabled. If CFG1 and CFG0 are high (SDM) then this pin is pulled low.
PROGRAMN	I	Initiates configuration sequence when asserted low. This pin always has an active pull-up.
DONE	I/O	Open Drain pin - Indicates that the configuration sequence is complete, and the startup sequence is in progress.
CCLK	I/O	Configuration Clock for configuring an FPGA in sysCONFIG mode.
BUSY	I/O	Generally not used. After configuration it is a user-programmable I/O pin.
CSN	I	sysCONFIG chip select (Active low). During configuration, a pull-up is enabled. After configuration it is user a programmable I/O pin.
CS1N	I	sysCONFIG chip select (Active Low). During configuration, a pull-up is enabled. After configuration it is user programmable I/O pin
WRITEN	I	Write Data on Parallel port (Active low). After configuration it is a user programmable I/O pin
D[7:0]	I/O	sysCONFIG Port Data I/O. After configuration these are user programmable I/O pins.
DOUT, CSON	O	Output for serial configuration data (rising edge of CCLK) when using sysCONFIG port. After configuration, it is a user-programmable I/O pin.
DI	I	Input for serial configuration data (clocked with CCLK) when using sysCONFIG port. During configuration, a pull-up is enabled. After configuration it is a user-programmable I/O pin.
SLEEPN[2]	I	Sleep Mode pin - Active low sleep pin.þ When this pin is held high, the device operates normally.þ When driven low, the device moves into Sleep Mode after a specified time.This pin has a weak internal pull-up, but when not used an external pull-up to V_{CC} is recommended.
TOE[3]	I	Test Output Enable tri-states all I/O pins when driven low. This pin has a weak internal pull-up, but when not used an external pull-up to V_{CC} is recommended.

1. Applies toþ LFXP10, LFXP15 and LFXP20 only.
2. Applies to LFXP “C” devices only.
3. Applies to LFXP “E” devices only.

LFXP3 & LFXP6 Logic Signal Connections: 144 TQFP (Cont.)

Pin Number	LFXP3				LFXP6			
	Pin Function	Bank	Differential	Dual Function	Pin Function	Bank	Differential	Dual Function
47	PB11A	5	T	DQS	PB14A	5	T	DQS
48	PB11B	5	C	-	PB14B	5	C	-
49	VCCIO5	5	-	-	VCCIO5	5	-	-
50	PB12A	5	T	-	PB15A	5	T	-
51	PB12B	5	C	-	PB15B	5	C	-
52	PB13A	5	T	-	PB16A	5	T	-
53	PB13B	5	C	-	PB16B	5	C	-
54	GND	-	-	-	GND	-	-	-
55	PB14A	4	T	-	PB17A	4	T	-
56	GNDIO4	4	-	-	GNDIO4	4	-	-
57	PB14B	4	C	-	PB17B	4	C	-
58	PB15A	4	T	PCLKT4_0	PB18A	4	T	PCLKT4_0
59	PB15B	4	C	PCLKC4_0	PB18B	4	C	PCLKC4_0
60	PB16A	4	T	-	PB19A	4	T	-
61	VCCIO4	4	-	-	VCCIO4	4	-	-
62	PB16B	4	C	-	PB19B	4	C	-
63	PB19A	4	T	DQS	PB22A	4	T	DQS
64	GNDIO4	4	-	-	GNDIO4	4	-	-
65	PB19B	4	C	VREF1_4	PB22B	4	C	VREF1_4
66	PB20A	4	T	-	PB23A	4	T	-
67	PB20B	4	C	-	PB23B	4	C	-
68	VCCIO4	4	-	-	VCCIO4	4	-	-
69	PB22A	4	-	-	PB25A	4	-	-
70	PB24A	4	T	VREF2_4	PB27A	4	T	VREF2_4
71	PB24B	4	C	-	PB27B	4	C	-
72	PB25A	4	-	-	PB28A	4	-	-
73	VCC	-	-	-	VCC	-	-	-
74	PR18B	3	C[3]	-	PR26B	3	C[3]	-
75	GNDIO3	3	-	-	GNDIO3	3	-	-
76	PR18A	3	T[3]	-	PR26A	3	T[3]	-
77	PR17B	3	C	-	PR25B	3	C	-
78	PR17A	3	T	-	PR25A	3	T	-
79	PR16B	3	C[3]	-	PR24B	3	C[3]	-
80	PR16A	3	T[3]	DQS	PR24A	3	T[3]	DQS
81	PR15B	3	-	VREF1_3	PR23B	3	-	VREF1_3
82	PR14A	3	-	VREF2_3	PR22A	3	-	VREF2_3
83	PR13B	3	C	-	PR21B	3	C[3]	-
84	PR13A	3	T	-	PR21A	3	T[3]	-
85	GND	-	-	-	GND	-	-	-
86	PR12A	3	-	-	PR20A	3	-	-
87	PR11B	3	C	-	PR19B	3	C[3]	-
88	VCCIO3	3	-	-	VCCIO3	3	-	-
89	PR11A	3	T	-	PR19A	3	T[3]	-
90	GNDP1	-	-	-	GNDP1	-	-	-
91	VCCP1	-	-	-	VCCP1	-	-	-
92	PR9B	2	C	PCLKC2_0	PR12B	2	C	PCLKC2_0

LFXP15 & LFXP20 Logic Signal Connections: 256 fpBGA (Cont.)

	LFXP15				LFXP20			
Ball Number	Ball Function	Bank	Differential	Dual Function	Ball Function	Bank	Differential	Dual Function
L7	VCCIO5	5	-	-	VCCIO5	5	-	-
L8	VCCIO5	5	-	-	VCCIO5	5	-	-
J6	VCCIO6	6	-	-	VCCIO6	6	-	-
K6	VCCIO6	6	-	-	VCCIO6	6	-	-
G6	VCCIO7	7	-	-	VCCIO7	7	-	-
H6	VCCIO7	7	-	-	VCCIO7	7	-	-

1. Applies to LFXP “C” only.
2. Applies to LFXP “E” only.
3. Supports dedicated LVDS outputs.

LFXP10, LFXP15 & LFXP20 Logic Signal Connections: 388 fpBGA (Cont.)

	LFXP10				LFXP15				LFXP20			
Ball Number	Ball Function	Bank	Diff.	Dual Function	Ball Function	Bank	Diff.	Dual Function	Ball Function	Bank	Diff.	Dual Function
A7	PT13A	0	T	DI	PT18A	0	T	DI	PT22A	0	T	DI
B7	PT12B	0	C	-	PT17B	0	C	-	PT21B	0	C	-
C6	PT12A	0	T	CSN	PT17A	0	T	CSN	PT21A	0	T	CSN
C10	PT11B	0	C	-	PT16B	0	C	-	PT20B	0	C	-
C9	PT11A	0	T	-	PT16A	0	T	-	PT20A	0	T	-
A6	PT10B	0	C	VREF2_0	PT15B	0	C	VREF2_0	PT19B	0	C	VREF2_0
B6	PT10A	0	T	DQS	PT15A	0	T	DQS	PT19A	0	T	DQS
A5	PT9B	0	-	-	PT14B	0	-	-	PT18B	0	-	-
B5	PT8A	0	-	-	PT13A	0	-	-	PT17A	0	-	-
-	GNDIO0	0	-	-	GNDIO0	0	-	-	GNDIO0	0	-	-
C5	PT7B	0	C	-	PT12B	0	C	-	PT16B	0	C	-
A4	PT7A	0	T	-	PT12A	0	T	-	PT16A	0	T	-
D9	PT6B	0	C	-	PT11B	0	C	-	PT15B	0	C	-
D8	PT6A	0	T	-	PT11A	0	T	-	PT15A	0	T	-
B4	PT5B	0	C	-	PT10B	0	C	-	PT14B	0	C	-
A2	PT5A	0	T	-	PT10A	0	T	-	PT14A	0	T	-
A3	PT4B	0	C	-	PT9B	0	C	-	PT13B	0	C	-
B3	PT4A	0	T	-	PT9A	0	T	-	PT13A	0	T	-
C4	PT3B	0	C	-	PT8B	0	C	-	PT12B	0	C	-
C3	PT3A	0	T	-	PT8A	0	T	-	PT12A	0	T	-
-	GNDIO0	0	-	-	GNDIO0	0	-	-	GNDIO0	0	-	-
C2	-	-	-	-	PT7B	0	C	-	PT11B	0	C	-
D3	PT2A	0	-	-	PT7A	0	T	DQS	PT11A	0	T	DQS
D7	-	-	-	-	PT6B	0	-	-	PT10B	0	-	-
D6	-	-	-	-	PT5A	0	-	-	PT9A	0	-	-
E4	-	-	-	-	PT4B	0	C	-	PT8B	0	C	-
D4	-	-	-	-	PT4A	0	T	-	PT8A	0	T	-
D5	-	-	-	-	PT3B	0	-	-	PT7B	0	-	-
-	GNDIO0	0	-	-	GNDIO0	0	-	-	GNDIO0	0	-	-
-	GNDIO0	0	-	-	GNDIO0	0	-	-	GNDIO0	0	-	-
C1	CFG0	0	-	-	CFG0	0	-	-	CFG0	0	-	-
B2	CFG1	0	-	-	CFG1	0	-	-	CFG1	0	-	-
B1	DONE	0	-	-	DONE	0	-	-	DONE	0	-	-
A1	GND	-	-	-	GND	-	-	-	GND	-	-	-
A22	GND	-	-	-	GND	-	-	-	GND	-	-	-
AB1	GND	-	-	-	GND	-	-	-	GND	-	-	-
AB22	GND	-	-	-	GND	-	-	-	GND	-	-	-
H10	GND	-	-	-	GND	-	-	-	GND	-	-	-
H11	GND	-	-	-	GND	-	-	-	GND	-	-	-
H12	GND	-	-	-	GND	-	-	-	GND	-	-	-
H13	GND	-	-	-	GND	-	-	-	GND	-	-	-
H14	GND	-	-	-	GND	-	-	-	GND	-	-	-
J10	GND	-	-	-	GND	-	-	-	GND	-	-	-
J11	GND	-	-	-	GND	-	-	-	GND	-	-	-
J12	GND	-	-	-	GND	-	-	-	GND	-	-	-
J13	GND	-	-	-	GND	-	-	-	GND	-	-	-
J14	GND	-	-	-	GND	-	-	-	GND	-	-	-
J9	GND	-	-	-	GND	-	-	-	GND	-	-	-
K10	GND	-	-	-	GND	-	-	-	GND	-	-	-

LFXP10, LFXP15 & LFXP20 Logic Signal Connections: 388 fpBGA (Cont.)

	LFXP10				LFXP15				LFXP20			
Ball Number	Ball Function	Bank	Diff.	Dual Function	Ball Function	Bank	Diff.	Dual Function	Ball Function	Bank	Diff.	Dual Function
K11	GND	-	-	-	GND	-	-	-	GND	-	-	-
K12	GND	-	-	-	GND	-	-	-	GND	-	-	-
K13	GND	-	-	-	GND	-	-	-	GND	-	-	-
K14	GND	-	-	-	GND	-	-	-	GND	-	-	-
K9	GND	-	-	-	GND	-	-	-	GND	-	-	-
L10	GND	-	-	-	GND	-	-	-	GND	-	-	-
L11	GND	-	-	-	GND	-	-	-	GND	-	-	-
L12	GND	-	-	-	GND	-	-	-	GND	-	-	-
L13	GND	-	-	-	GND	-	-	-	GND	-	-	-
L14	GND	-	-	-	GND	-	-	-	GND	-	-	-
L9	GND	-	-	-	GND	-	-	-	GND	-	-	-
M10	GND	-	-	-	GND	-	-	-	GND	-	-	-
M11	GND	-	-	-	GND	-	-	-	GND	-	-	-
M12	GND	-	-	-	GND	-	-	-	GND	-	-	-
M13	GND	-	-	-	GND	-	-	-	GND	-	-	-
M14	GND	-	-	-	GND	-	-	-	GND	-	-	-
M9	GND	-	-	-	GND	-	-	-	GND	-	-	-
N10	GND	-	-	-	GND	-	-	-	GND	-	-	-
N11	GND	-	-	-	GND	-	-	-	GND	-	-	-
N12	GND	-	-	-	GND	-	-	-	GND	-	-	-
N13	GND	-	-	-	GND	-	-	-	GND	-	-	-
N14	GND	-	-	-	GND	-	-	-	GND	-	-	-
N9	GND	-	-	-	GND	-	-	-	GND	-	-	-
P10	GND	-	-	-	GND	-	-	-	GND	-	-	-
P11	GND	-	-	-	GND	-	-	-	GND	-	-	-
P12	GND	-	-	-	GND	-	-	-	GND	-	-	-
P13	GND	-	-	-	GND	-	-	-	GND	-	-	-
P14	GND	-	-	-	GND	-	-	-	GND	-	-	-
P9	GND	-	-	-	GND	-	-	-	GND	-	-	-
R10	GND	-	-	-	GND	-	-	-	GND	-	-	-
R11	GND	-	-	-	GND	-	-	-	GND	-	-	-
R12	GND	-	-	-	GND	-	-	-	GND	-	-	-
R13	GND	-	-	-	GND	-	-	-	GND	-	-	-
R14	GND	-	-	-	GND	-	-	-	GND	-	-	-
H9	VCC	-	-	-	VCC	-	-	-	VCC	-	-	-
J15	VCC	-	-	-	VCC	-	-	-	VCC	-	-	-
J8	VCC	-	-	-	VCC	-	-	-	VCC	-	-	-
K15	VCC	-	-	-	VCC	-	-	-	VCC	-	-	-
K8	VCC	-	-	-	VCC	-	-	-	VCC	-	-	-
L15	VCC	-	-	-	VCC	-	-	-	VCC	-	-	-
L8	VCC	-	-	-	VCC	-	-	-	VCC	-	-	-
M15	VCC	-	-	-	VCC	-	-	-	VCC	-	-	-
M8	VCC	-	-	-	VCC	-	-	-	VCC	-	-	-
N15	VCC	-	-	-	VCC	-	-	-	VCC	-	-	-
N8	VCC	-	-	-	VCC	-	-	-	VCC	-	-	-
P15	VCC	-	-	-	VCC	-	-	-	VCC	-	-	-
P8	VCC	-	-	-	VCC	-	-	-	VCC	-	-	-
R9	VCC	-	-	-	VCC	-	-	-	VCC	-	-	-
G16	VCCAUX	-	-	-	VCCAUX	-	-	-	VCCAUX	-	-	-

LFXP10, LFXP15 & LFXP20 Logic Signal Connections: 388 fpBGA (Cont.)

	LFXP10				LFXP15				LFXP20			
Ball Number	Ball Function	Bank	Diff.	Dual Function	Ball Function	Bank	Diff.	Dual Function	Ball Function	Bank	Diff.	Dual Function
G7	VCCAUX	-	-	-	VCCAUX	-	-	-	VCCAUX	-	-	-
T16	VCCAUX	-	-	-	VCCAUX	-	-	-	VCCAUX	-	-	-
T7	VCCAUX	-	-	-	VCCAUX	-	-	-	VCCAUX	-	-	-
G10	VCCIO0	0	-	-	VCCIO0	0	-	-	VCCIO0	0	-	-
G11	VCCIO0	0	-	-	VCCIO0	0	-	-	VCCIO0	0	-	-
G8	VCCIO0	0	-	-	VCCIO0	0	-	-	VCCIO0	0	-	-
G9	VCCIO0	0	-	-	VCCIO0	0	-	-	VCCIO0	0	-	-
H8	VCCIO0	0	-	-	VCCIO0	0	-	-	VCCIO0	0	-	-
G12	VCCIO1	1	-	-	VCCIO1	1	-	-	VCCIO1	1	-	-
G13	VCCIO1	1	-	-	VCCIO1	1	-	-	VCCIO1	1	-	-
G14	VCCIO1	1	-	-	VCCIO1	1	-	-	VCCIO1	1	-	-
G15	VCCIO1	1	-	-	VCCIO1	1	-	-	VCCIO1	1	-	-
H15	VCCIO1	1	-	-	VCCIO1	1	-	-	VCCIO1	1	-	-
H16	VCCIO2	2	-	-	VCCIO2	2	-	-	VCCIO2	2	-	-
J16	VCCIO2	2	-	-	VCCIO2	2	-	-	VCCIO2	2	-	-
K16	VCCIO2	2	-	-	VCCIO2	2	-	-	VCCIO2	2	-	-
L16	VCCIO2	2	-	-	VCCIO2	2	-	-	VCCIO2	2	-	-
M16	VCCIO3	3	-	-	VCCIO3	3	-	-	VCCIO3	3	-	-
N16	VCCIO3	3	-	-	VCCIO3	3	-	-	VCCIO3	3	-	-
P16	VCCIO3	3	-	-	VCCIO3	3	-	-	VCCIO3	3	-	-
R16	VCCIO3	3	-	-	VCCIO3	3	-	-	VCCIO3	3	-	-
R15	VCCIO4	4	-	-	VCCIO4	4	-	-	VCCIO4	4	-	-
T12	VCCIO4	4	-	-	VCCIO4	4	-	-	VCCIO4	4	-	-
T13	VCCIO4	4	-	-	VCCIO4	4	-	-	VCCIO4	4	-	-
T14	VCCIO4	4	-	-	VCCIO4	4	-	-	VCCIO4	4	-	-
T15	VCCIO4	4	-	-	VCCIO4	4	-	-	VCCIO4	4	-	-
R8	VCCIO5	5	-	-	VCCIO5	5	-	-	VCCIO5	5	-	-
T10	VCCIO5	5	-	-	VCCIO5	5	-	-	VCCIO5	5	-	-
T11	VCCIO5	5	-	-	VCCIO5	5	-	-	VCCIO5	5	-	-
T8	VCCIO5	5	-	-	VCCIO5	5	-	-	VCCIO5	5	-	-
T9	VCCIO5	5	-	-	VCCIO5	5	-	-	VCCIO5	5	-	-
M7	VCCIO6	6	-	-	VCCIO6	6	-	-	VCCIO6	6	-	-
N7	VCCIO6	6	-	-	VCCIO6	6	-	-	VCCIO6	6	-	-
P7	VCCIO6	6	-	-	VCCIO6	6	-	-	VCCIO6	6	-	-
R7	VCCIO6	6	-	-	VCCIO6	6	-	-	VCCIO6	6	-	-
H7	VCCIO7	7	-	-	VCCIO7	7	-	-	VCCIO7	7	-	-
J7	VCCIO7	7	-	-	VCCIO7	7	-	-	VCCIO7	7	-	-
K7	VCCIO7	7	-	-	VCCIO7	7	-	-	VCCIO7	7	-	-
L7	VCCIO7	7	-	-	VCCIO7	7	-	-	VCCIO7	7	-	-

1. Applies to LFXP “C” only.
2. Applies to LFXP “E” only.
3. Supports dedicated LVDS outputs.

LFXP15 & LFXP20 Logic Signal Connections: 484 fpBGA (Cont.)

	LFXP15				LFXP20			
Ball Number	Ball Function	Bank	Differential	Dual Function	Ball Function	Bank	Differential	Dual Function
AB5	PB16A	5	T	-	PB20A	5	T	-
AB6	PB16B	5	C	-	PB20B	5	C	-
AA8	PB17A	5	T	-	PB21A	5	T	-
AA9	PB17B	5	C	VREF2_5	PB21B	5	C	VREF2_5
W10	PB18A	5	T	-	PB22A	5	T	-
-	GNDIO5	5	-	-	GNDIO5	5	-	-
V10	PB18B	5	C	-	PB22B	5	C	-
AB7	PB19A	5	T	-	PB23A	5	T	-
AB8	PB19B	5	C	-	PB23B	5	C	-
AB9	PB20A	5	T	-	PB24A	5	T	-
AB10	PB20B	5	C	-	PB24B	5	C	-
Y10	PB21A	5	-	-	PB25A	5	-	-
AA10	PB22B	5	-	-	PB26B	5	-	-
W11	PB23A	5	T	DQS	PB27A	5	T	DQS
V11	PB23B	5	C	-	PB27B	5	C	-
-	GNDIO5	5	-	-	GNDIO5	5	-	-
Y11	PB24A	5	T	-	PB28A	5	T	-
AA11	PB24B	5	C	-	PB28B	5	C	-
AB11	PB25A	5	T	-	PB29A	5	T	-
AB12	PB25B	5	C	-	PB29B	5	C	-
Y12	PB26A	4	T	-	PB30A	4	T	-
AA12	PB26B	4	C	-	PB30B	4	C	-
W12	PB27A	4	T	PCLKT4_0	PB31A	4	T	PCLKT4_0
V12	PB27B	4	C	PCLKC4_0	PB31B	4	C	PCLKC4_0
-	GNDIO4	4	-	-	GNDIO4	4	-	-
AB13	PB28A	4	T	-	PB32A	4	T	-
AB14	PB28B	4	C	-	PB32B	4	C	-
AA13	PB29A	4	-	-	PB33A	4	-	-
Y13	PB30B	4	-	-	PB34B	4	-	-
AB15	PB31A	4	T	DQS	PB35A	4	T	DQS
AB16	PB31B	4	C	VREF1_4	PB35B	4	C	VREF1_4
V13	PB32A	4	T	-	PB36A	4	T	-
W13	PB32B	4	C	-	PB36B	4	C	-
AA14	PB33A	4	T	-	PB37A	4	T	-
-	GNDIO4	4	-	-	GNDIO4	4	-	-
AA15	PB33B	4	C	-	PB37B	4	C	-
AB17	PB34A	4	T	-	PB38A	4	T	-
AB18	PB34B	4	C	-	PB38B	4	C	-
W14	PB35A	4	T	-	PB39A	4	T	-
Y14	PB35B	4	C	-	PB39B	4	C	-
U14	PB36A	4	T	VREF2_4	PB40A	4	T	VREF2_4
V14	PB36B	4	C	-	PB40B	4	C	-

LFXP15 & LFXP20 Logic Signal Connections: 484 fpBGA (Cont.)

	LFXP15				LFXP20			
Ball Number	Ball Function	Bank	Differential	Dual Function	Ball Function	Bank	Differential	Dual Function
AB19	PB37A	4	-	-	PB41A	4	-	-
AB20	PB38B	4	-	-	PB42B	4	-	-
-	GNDIO4	4	-	-	GNDIO4	4	-	-
V15	PB39A	4	T	DQS	PB43A	4	T	DQS
U15	PB39B	4	C	-	PB43B	4	C	-
Y15	PB40A	4	T	-	PB44A	4	T	-
W15	PB40B	4	C	-	PB44B	4	C	-
AA16	PB41A	4	T	-	PB45A	4	T	-
AA17	PB41B	4	C	-	PB45B	4	C	-
AA18	PB42A	4	T	-	PB46A	4	T	-
AA19	PB42B	4	C	-	PB46B	4	C	-
Y16	PB43A	4	T	-	PB47A	4	T	-
W16	PB43B	4	C	-	PB47B	4	C	-
-	GNDIO4	4	-	-	GNDIO4	4	-	-
AA20	PB44A	4	T	-	PB48A	4	T	-
AA21	PB44B	4	C	-	PB48B	4	C	-
Y17	PB45A	4	-	-	PB49A	4	-	-
Y18	PB46B	4	-	-	PB50B	4	-	-
Y19	PB47A	4	T	DQS	PB51A	4	T	DQS
Y20	PB47B	4	C	-	PB51B	4	C	-
V16	PB48A	4	T	-	PB52A	4	T	-
U16	PB48B	4	C	-	PB52B	4	C	-
-	GNDIO4	4	-	-	GNDIO4	4	-	-
U18	-	-	-	-	PB53A	4	T	-
V18	-	-	-	-	PB53B	4	C	-
W19	-	-	-	-	PB54A	4	T	-
W18	-	-	-	-	PB54B	4	C	-
U17	-	-	-	-	PB55A	4	T	-
V17	-	-	-	-	PB55B	4	C	-
-	GNDIO4	4	-	-	GNDIO4	4	-	-
W17	-	-	-	-	PB56A	4	-	-
-	GNDIO3	3	-	-	GNDIO3	3	-	-
V19	PR43A	3	-	-	PR47A	3	-	-
U20	PR42B	3	C[3]	-	PR46B	3	C[3]	-
U19	PR42A	3	T[3]	-	PR46A	3	T[3]	-
V20	PR41B	3	C	-	PR45B	3	C	-
W20	PR41A	3	T	-	PR45A	3	T	-
T17	PR40B	3	C[3]	-	PR44B	3	C[3]	-
T18	PR40A	3	T[3]	-	PR44A	3	T[3]	-
T19	PR39B	3	C[3]	-	PR43B	3	C[3]	-
T20	PR39A	3	T[3]	-	PR43A	3	T[3]	-
-	GNDIO3	3	-	-	GNDIO3	3	-	-

LFXP15 & LFXP20 Logic Signal Connections: 484 fpBGA (Cont.)

	LFXP15				LFXP20			
Ball Number	Ball Function	Bank	Differential	Dual Function	Ball Function	Bank	Differential	Dual Function
H13	VCCIO1	1	-	-	VCCIO1	1	-	-
K15	VCCIO2	2	-	-	VCCIO2	2	-	-
L15	VCCIO2	2	-	-	VCCIO2	2	-	-
L16	VCCIO2	2	-	-	VCCIO2	2	-	-
L17	VCCIO2	2	-	-	VCCIO2	2	-	-
M15	VCCIO3	3	-	-	VCCIO3	3	-	-
M16	VCCIO3	3	-	-	VCCIO3	3	-	-
M17	VCCIO3	3	-	-	VCCIO3	3	-	-
N15	VCCIO3	3	-	-	VCCIO3	3	-	-
R12	VCCIO4	4	-	-	VCCIO4	4	-	-
R13	VCCIO4	4	-	-	VCCIO4	4	-	-
T12	VCCIO4	4	-	-	VCCIO4	4	-	-
U12	VCCIO4	4	-	-	VCCIO4	4	-	-
R10	VCCIO5	5	-	-	VCCIO5	5	-	-
R11	VCCIO5	5	-	-	VCCIO5	5	-	-
T11	VCCIO5	5	-	-	VCCIO5	5	-	-
U11	VCCIO5	5	-	-	VCCIO5	5	-	-
M6	VCCIO6	6	-	-	VCCIO6	6	-	-
M7	VCCIO6	6	-	-	VCCIO6	6	-	-
M8	VCCIO6	6	-	-	VCCIO6	6	-	-
N8	VCCIO6	6	-	-	VCCIO6	6	-	-
K8	VCCIO7	7	-	-	VCCIO7	7	-	-
L6	VCCIO7	7	-	-	VCCIO7	7	-	-
L7	VCCIO7	7	-	-	VCCIO7	7	-	-
L8	VCCIO7	7	-	-	VCCIO7	7	-	-

1. Applies to LFXP “C” only.
2. Applies to LFXP “E” only.
3. Supports dedicated LVDS outputs.

Thermal Management

Thermal management is recommended as part of any sound FPGA design methodology. To assess the thermal characteristics of a system, Lattice specifies a maximum allowable junction temperature in all device data sheets. Designers must complete a thermal analysis of their specific design to ensure that the device and package do not exceed the junction temperature limits. Refer to the Thermal Management document to find the device/package specific thermal values.

For Further Information

For further information regarding Thermal Management, refer to the following located on the Lattice website at www.latticesemi.com.

- Thermal Management document
- Technical Note TN1052 - Power Estimation and Management for LatticeECP/EC and LatticeXP Devices
- Power Calculator tool included with Lattice's ispLEVER design tool, or as a standalone download from www.latticesemi.com/software

LatticeXP Family Data Sheet
Revision History

November 2007 **Data Sheet DS1001**

Revision History

Date	Version	Section	Change Summary
February 2005	01.0	—	Initial release.
April 2005	01.1	Architecture	EBR memory support section updated with clarification.
May 2005	01.2	Introduction	Added TransFR Reconfiguration to Features section.
		Architecture	Added TransFR section.
June 2005	01.3	Pinout Information	Added pinout information for LFXP3, LFXP6, LFXP15 and LFXP20.
July 2005	02.0	Introduction	Updated XP6, XP15 and XP20 EBR SRAM Bits and Block numbers.
		Architecture	Updated Per Quadrant Primary Clock Selection figure.
			Added Typical I/O Behavior During Power-up section.
			Updated Device Configuration section under Configuration and Testing.
		DC and Switching Characteristics	Clarified Hot Socketing Specification
			Updated Supply Current (Standby) Table
			Updated Initialization Supply Current Table
			Added Programming and Erase Flash Supply Current table
			Added LVDS Emulation section. Updated LVDS25E Output Termination Example figure and LVDS25E DC Conditions table.
			Updated Differential LVPECL diagram and LVPECL DC Conditions table.
			Deleted 5V Tolerant Input Buffer section. Updated RSDS figure and RSDS DC Conditions table.
			Updated sysCONFIG Port Timing Specifications
			Updated JTAG Port Timing Specifications. Added Flash Download Time table.
		Pinout Information	Updated Signal Descriptions table.
			Updated Logic Signal Connections Dual Function column.
		Ordering Information	Added lead-free ordering part numbers.
July 2005	02.1	DC and Switching Characteristics	Clarification of Flash Programming Junction Temperature
August 2005	02.2	Introduction	Added Sleep Mode feature.
		Architecture	Added Sleep Mode section.
		DC and Switching Characteristics	Added Sleep Mode Supply Current Table
			Added Sleep Mode Timing section
		Pinout Information	Added SLEEPN and TOE signal names, descriptions and footnotes.
			Added SLEEPN and TOE to pinout information and footnotes.
			Added footnote 3 to Logic Signal Connections tables for clarification on emulated LVDS output.
September 2005	03.0	Architecture	Added clarification of PCI clamp.
			Added clarification to SLEEPN Pin Characteristics section.
		DC and Switching Characteristics	DC Characteristics, added footnote 4 for clarification. Updated Supply Current (Sleep Mode), Supply Current (Standby), Initialization Supply Current, and Programming and Erase Flash Supply Current typical numbers.